



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2020-02-04
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement	
<b>Supplier Acceptance *</b>	true
<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDO7*0507AT6	A	BO2A	2020-02-04
Amount	UoM	Unit type	ST ECOPACK Grade	
76.5	mg	Each	ECOPACK® 3	
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9 x 6	8	gull wing	
Comment	07 SO 08 .15 JEDEC; MDF is valid for TSS07IDT and TSS07CDT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.43	leadframe	5621

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
,			,	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update				
Query				Response
The Product does contain at least one of the substances listed in Chemical Control Act				NO
Substance	Homogeneous Material impacted	Content in Homogeneous Material (mg)	Concentration in the material(%)	Application Purpose

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	IDO7*0507AT6				5000001.0	1000002.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.885	mg	supplier	die	Silicon(Si)	7440-21-3		0.871	mg	984181	11386
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.003	mg	3390	39
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	1130	13
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.002	mg	2260	26
				supplier	passivation	Silicon oxide	7631-86-9		0.008	mg	9040	105
Leadframe	M-004 Copper and its alloys	28.917	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		27.705	mg	958087	362157
				supplier	alloy & coating	Nickel(Ni)	7440-02-0		0.430	mg	14870	5621
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.652	mg	22547	8523
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.039	mg	1349	510
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.034	mg	1176	444
				supplier	alloy & coating	Silver (Ag)	7440-22-4		0.015	mg	519	196
				supplier	alloy & coating	Palladium(Pd)	7440-05-3		0.035	mg	1210	458
				supplier	alloy & coating	Gold(Au)	7440-57-5		0.007	mg	242	92
Die attach	M-015 Other organic materials	0.207	mg	supplier	glue	Silver(Ag)	7440-22-4		0.183	mg	884058	2392
				supplier	glue	Isobornyl methacrylate	7534-94-3		0.010	mg	48309	131
				supplier	glue	Isobornyl acrylate	5888-33-5		0.010	mg	48309	131
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.004	mg	19324	52
Bonding wires	M-004 Copper and its alloys	0.027	mg	supplier	wire	Copper(Cu)	7440-50-8		0.027	mg	1000000	353
Encapsulation	M-011 Other inorganic materials	46.464	mg	supplier	mold compound	Silica vitreous	60676-86-0		40.238	mg	866004	525987
				supplier	mold compound	Epoxy type resin	proprietary		3.485	mg	75004	45556
				supplier	mold compound	Phenol type resin	proprietary		2.323	mg	49996	30366
				supplier	mold compound	Carbon black	1333-86-4		0.232	mg	4993	3033
				supplier	mold compound	Bismuth compound	7440-69-9		0.186	mg	4003	2431